

What is claimed is:

- Sub A1* ~~1. A tape carrier type semiconductor device comprising:
a flexible substrate on whose surface wiring is formed; and
a driver circuit which is mounted on said flexible substrate and drives a device
connected to said flexible substrate, and~~
- 5 ~~wherein said flexible substrate includes a first slit having a connector for connecting
both sides of the first slit.~~
2. The tape carrier type semiconductor device according to claim 1, wherein the
first slit includes a plurality of connectors.
3. The tape carrier type semiconductor device according to claim 2, wherein
parts of the slit, which are separated from each other at the connector, are diverged from
each other at the connector in a direction perpendicular to the slit.
4. The tape carrier type semiconductor device according to claim 3, wherein said
flexible substrate includes a plurality of first slits.
5. The tape carrier type semiconductor device according to claim 4, wherein said
flexible substrate includes a second slit for folding said tape carrier type semiconductor
device.
- Sub A2* ~~6. The tape carrier type semiconductor device according to claim 5, wherein said
flexible substrate includes a rib which is formed substantially perpendicular to the
plurality of first slits.~~
7. The tape carrier type semiconductor device according to claim 6, a portion of
said flexible substrate is changed in shape, thereby to form the rib.
- Sub A3* ~~8. The tape carrier type semiconductor device according to claim 1, wherein said
flexible substrate includes a rib which is formed substantially perpendicular to the first
slit.~~
9. The tape carrier type semiconductor device according to claim 8, wherein a
portion of said flexible substrate is changed in shape, thereby to form the rib.

- sub a4*
10. A tape carrier type semiconductor device comprising:
a flexible substrate on whose surface wiring is formed; and
a driver circuit which is mounted on said flexible substrate and drives a device
connected to said flexible substrate, and
- 5 wherein said flexible substrate includes a slit for folding said flexible substrate and a
rib which is formed substantially perpendicular to the slit.
11. The tape carrier type semiconductor device according to claim 10, a portion
of said flexible substrate is changed in shape, thereby to form the rib.
- sub a5*
12. A method for manufacturing a carrier type semiconductor device, comprising
forming a rib for reducing a warp of a flexible film on and in which a driver circuit and a
slit are formed, by changing a shape of the flexible film, when the flexible film is cut into
a predetermined length.
13. A flexible substrate, which includes a first slit having a connector for
connecting both sides of the first slit, and on whose surface wiring having a
predetermined pattern is formed.
14. The flexible substrate according to claim 13, wherein the first slit includes a
plurality of connectors.
15. The flexible substrate according to claim 14, wherein parts of the slit, which
are separated from each other at the connector, are diverged from each other at the
connector in a direction perpendicular to the slit.
16. The flexible substrate according to claim 15, further comprising a second slit
for folding said flexible substrate.
17. The flexible substrate according to claim 16, further comprising a rib formed
substantially perpendicular to the first slit.
18. The flexible substrate according to claim 17, wherein a portion of said
flexible substrate is changed in shape, thereby to form the rib.
- Add a6*